



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC0503NSI		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA001295948						
<b>Package</b>		PG-TDSON-8-6		<b>Weight*</b>		115.49 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.267	0.23	0.23	2310	2310
leadframe	non noble metal	iron	7439-89-6	0.049	0.04		426	
	inorganic material	phosphorus	7723-14-0	0.015	0.01		128	
	non noble metal	copper	7440-50-8	49.082	42.51	42.56	425001	425555
wire	non noble metal	copper	7440-50-8	0.025	0.02	0.02	214	214
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		721	
	plastics	epoxy resin	-	5.914	5.12		51207	
	inorganic material	silicondioxide	60676-86-0	35.649	30.87	36.06	308686	360614
leadfinish	non noble metal	tin	7440-31-5	1.470	1.27	1.27	12727	12727
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1433	1433
solder	noble metal	silver	7440-22-4	0.011	0.01		97	
	non noble metal	tin	7440-31-5	0.009	0.01		77	
	non noble metal	lead	7439-92-1	0.427	0.37	0.39	3698	3872
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		193	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		58	
	non noble metal	copper	7440-50-8	22.292	19.30	19.33	193024	193275
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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